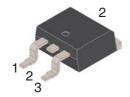
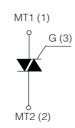


TO-252AA (DPAK)





On-State Current

Gate Trigger Current

4 Amp

< 10 mA

Off-State Voltage

400 V ÷ 800 V

FEATURES

- Glass/passivated die junctions
- Medium current Triac
- Ideal for automated placement
- Low thermal resistance
- High surge current capability
- Low forward voltage drop
- Solder dip 260°C, 10s
- Component in accordance to RoHS 2011/65/EU and WEEE 2002/96/EC
- Meets MSL level 3, per J-STD-020, LF maximum peak of 260° C



- Case: TO-252AA (DPAK). Epoxy meets UL 94V-0 flammability rating.
- Polarity: As marked on the body.
- **Terminals:** Matte tin plated leads, solderable per MIL-STD-750 Method 2026, J-STD-002 and JESD22-B102. Consumer grade, meets JESD 201 class 1A whisker test.

TYPICAL APPLICATIONS

Logic level versions are designed to interface directly with low power drivers such as microcontrollers.

Maximun Ratings and Electrical Characteristics at 25°C

SYMBOL	PARAMETER	CONDITIONS	Value	Unit
I _{T(RMS)}	RMS On-state Current (full sine wave)	All Conduction Angle, T _c =95 °C	4	А
I _{TSM}	Non-repetitive On-State Current	Full Cycle, 60 Hz (t = 16.7 ms)	33	А
I _{TSM}	Non-repetitive On-State Current	Full Cycle, 50 Hz (t = 20 ms)	30	А
I ² t	Fusing Current	tp = 10 ms, Half Cycle	4.5	A ² s
I _{GM}	Peak Gate Current	20 μs max. Tj = 125 °C	4	А
P _{G(AV)}	Average Gate Power Dissipation	Tj = 125 °C	1	W
dI/dt	Critical rate of rise of on-state current	$I_G = 2x I_{GT}, t_r \le 100 \text{ns}$	50	A/µs
		f = 120 Hz, T _j = 125 °C		
T _j	Operating Temperature		(-40 +125)	°C
T _{stg}	Storage Temperature		(-40 +150)	°C
T _{sld}	Soldering Temperature	10s max	260	°C

SYMBOL	PARAMETER	VOLTAGE				Unit
OTIVIBUL	774040121	D	М	S	N	
V_{DRM}/V_{RRM}	Repetitive Peak Off State Voltage	400	600	700	800	V

Revision: 1

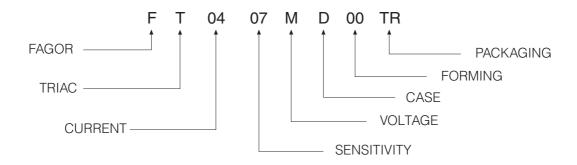


Electrical Characteristics at Tamb = 25 °C

SYMBOL PARAMETER		CONDITION	9	Quadrant SENSITIVIT		TIVITY	— Unit	
STIVIDOL	FANAIVILTEN	CONDITIONS		Quadrant		07	08	Offic
I _{GT} ⁽¹⁾	Gate Trigger Current	$V_D = 12 V_{DC}, R_L = 33 \Omega,$	$T_j = 25 ^{\circ}C$	Q1÷Q3	MAX	5	10	mA
				Q4	MAX	7		mA
V _{GT}	Gate Trigger Voltage	$V_D = 12 V_{DC}, R_L = 33 \Omega, $	$T_j = 25 ^{\circ}C$	Q1÷Q3	MAX	1.	.3	V
				Q1÷Q4	MAX	1.	.3	V
V_{GD}	Gate Non Trigger Voltage	$V_D = V_{DRM}, R_L = 3.3 \; K\Omega, $	$T_j = 125 ^{\circ}\text{C}$	Q1÷Q3	3 MIN 0.2		V	
				Q1÷Q4	MIN	0	.2	V
I _H (2)	Holding Current	$I_T = 100 \text{ mA}$, Gate open	$T_j = 25 ^{\circ}\text{C}$		MAX	15	15	mA
IL	Latching Current	$I_{G} = 1.2 I_{GT}, T_{j} = 25 ^{\circ}\text{C}$		Q1,Q3	MAX		25	mA
				Q1,Q3,Q4	MAX	20		mA
				Q2	MAX	30	30	mA
dV/dt (2)	Critical Rate of Voltage Rise	$V_D = 0.67 \times V_{DRM}$, Gate of	pen		MIN	20	40	V/µs
		T _j = 125 °C						
(dl/dt)c (2)	Critical Rate of Current Rise	$(dv/dt)c = 0.1 V/\mu s$	$T_j = 125 ^{\circ}C$		MIN	1.8	2.7	A/ms
		$(dv/dt)c = 10 V/\mu s$	$T_j = 125 ^{\circ}\text{C}$		MIN	0.9	2.0	A/ms
		without snubber	$T_j = 125 ^{\circ}\text{C}$		MIN	-	-	
V _{TM} (2)	On-state Voltage	$I_T = 5.5 \text{ Amp, tp} = 380 \ \mu\text{s, } T_j = 25 \ ^{\circ}\text{C}$			MAX	1.	.6	V
V_{to} (2)	Threshold Voltage	$T_j = 125 ^{\circ}\text{C}$			MAX	0	.9	V
r _d (2)	Dynamic resistance	T _j = 125 °C			MAX	14	10	m Ω
I _{DRM} /I _{RRM}	Off-State Leakage Current	$V_D = V_{DRM}$,	$T_j = 125 ^{\circ}\text{C}$		MAX	0	.5	mA
		$V_R = V_{RRM}$,	$T_j = 25 ^{\circ}C$		MAX	Ę	5	μΑ
R _{th(j-c)}	Thermal Resistance Junction-Case	for AC 360° conduction angle				2	.2	°C/W
R _{th(j-a)}	Thermal Resistance Junction-Ambient	$S = 1 \text{ cm}^2$				7	0	°C/W

⁽¹⁾ Minimum I_{GT} is guaranted at 5% of I_{GT} max.

Part Number Information



Revision: 1

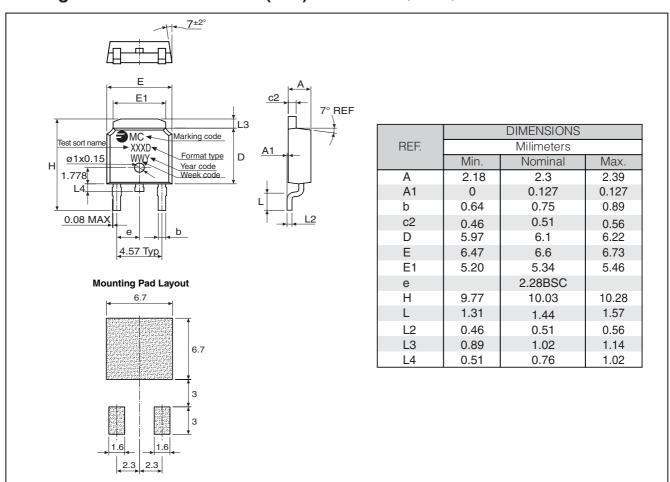
⁽²⁾ For either polarity of electrode MT2 voltage with reference to electrode MT1.



Ordering information

PREFERRED P/N	PACKAGE CODE	DELIVERY MODE	BASE QUANTITY	UNIT WEIGHT (g)
FT0407MD 00TR TR		13" diameter tape and reel	2,500	0.30

Package Outline Dimensions: (mm) TO-252AA (DPAK)





Ratings and Characteristics (Ta 25 °C unless otherwise noted)

Fig. 1: Maximum power dissipation versus RMS on-state current (full cycle).

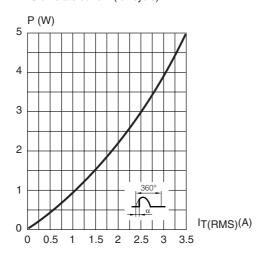


Fig. 3: Relative variation of thermal impedance versus pulse duration.

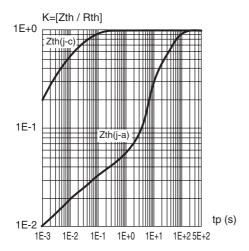


Fig. 5: Surge peak on-state current versus number of cycles

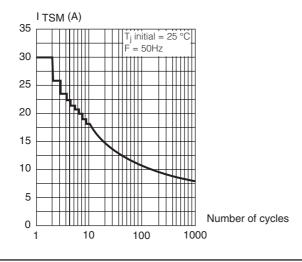


Fig. 2: RMS on-state current versus case temperature (full cycle).

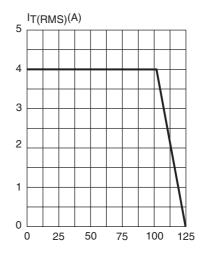


Fig. 4: On-state characteristics (maximum values)

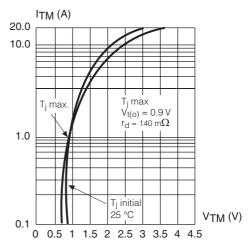
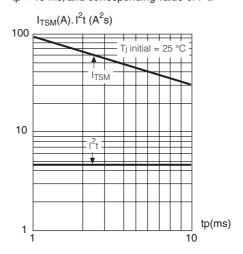


Fig. 6: Non repetitive surge peak on-state current for a sinusoidal pulse with width: tp < 10 ms, and corresponding value of I^2t .





Ratings and Characteristics (Ta 25 °C unless otherwise noted)

Fig. 7: Relative variation of gate trigger current, holding current and latching versus junction temperature (typical values)

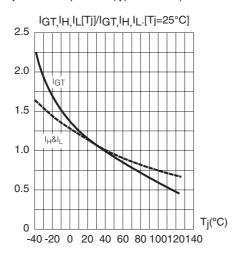


Fig. 9: Relative variation of critical rate of decrease of main current versus

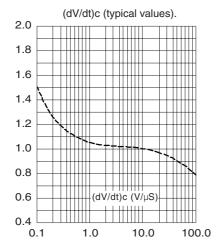
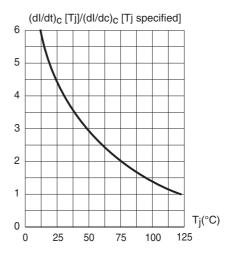


Fig. 8: Relative variation of critical rate of decrease of main current versus junction temperature





Revision History

Date	Revision	Description of Changes
14-Sep-2009 0		Original Data Sheet
21-May-2013	1	200V eliminated

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Revision: 1